

### Features

- -20V/-3A ,  
 $R_{DS(ON)} = 72m\Omega(\text{typ.}) @ V_{GS} = -4.5V$   
 $R_{DS(ON)} = 98m\Omega(\text{typ.}) @ V_{GS} = -2.5V$
- Super High Dense Cell Design
- Reliable and Rugged
- Lead Free Available (RoHS Compliant)

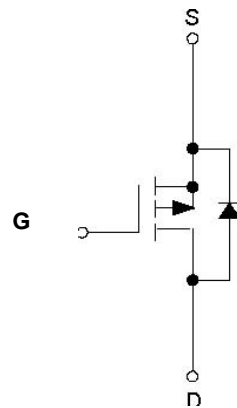
### Applications

- Power Management in Notebook Computer , Portable Equipment and Battery Powered Systems.

### Pin Description



Top View of SOT23-3L



P-Channel MOSFET

### Ordering and Marking Information

<p>TDM2301 □ □ - □ □ □</p> <ul style="list-style-type: none"> <li>□ □ □ : Lead Free Code</li> <li>□ □ : Handing Code</li> <li>□ : Temp. Range</li> <li>□ □ □ : Package Code</li> </ul>	<p>Package Code A: SOT23-3L</p> <p>Operating Junction Temp. Rang C: -55 to 150°C</p> <p>Handing Code TU:Tube TR:Tape &amp; Reel</p> <p>Lead Free Code: L:Lead Free Device Blank:Original Device</p>
<p>TDM2301 T01 X</p>	<p>X:Date Code</p>

**Note:** TECHCODE lead-free products contain molding compounds/die attach materials and 100% matte in plate termination finish; which are fully compliant with RoHS and compatible with both SnPb and lead-free soldering operations. TECHCODE lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J STD-020C for MSL classification at lead-free peak reflow temperature.

TECHCODE reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter		Rating	Unit
VDSS	Drain-Source Voltage		-20	V
VGSS	Gate-Source Voltage		$\pm 12$	
ID*	Continuous Drain Current		-3	A
IDM*	300 $\mu\text{s}$ Pulsed Drain Current	VGS=-4.5V	-10	
IS*	Diode Continuous Forward Current		-1	A
TJ	Maximum Junction Temperature		150	$^\circ\text{C}$
TSTG	Storage Temperature Range		-55 to 150	
PD*	Maximum Power Dissipation	TA=25 $^\circ\text{C}$	0.83	W
		TA=100 $^\circ\text{C}$	0.3	
R $\theta$ JA*	Thermal Resistance-Junction to Ambient		150	$^\circ\text{C}/\text{W}$

Note: \*

Surface Mounted on 1in<sup>2</sup> pad area,  $t \leq 10\text{sec}$ .Electrical Characteristics ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Condition	TDM2301			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V, ID=-250 $\mu\text{A}$	-20			V
IDSS	Zero Gate Voltage Drain Current	VDS=-16V, VGS=0V TJ=85 $^\circ\text{C}$			-1 -30	$\mu\text{A}$
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=-250 $\mu\text{A}$	-0.5	-0.6	-1	V
IGSS	Gate Leakage Current	VGS= $\pm 12\text{V}$ , VDS=0V			$\pm 100$	nA
RDS(ON) a	Drain-Source On-state Resistance	VGS=-4.5V, ID=-3A		72	90	m $\Omega$
		VGS=-2.5V, ID=-2A		98	115	
VSD a	Diode Forward Voltage	ISD=-1.25A, VGS=0V		-0.7	-1.3	V
<b>Gate Charge Characteristics</b> b						
Qg	Total Gate Charge	VDS=-10V, VGS=-4.5V, ID=-3A		9	12	
Qgs	Gate-Source Charge			3		nC
Qgd	Gate-Drain Charge			1.2		

Electrical Characteristics (Cont.) ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Condition	TDM2301			Unit
			Min.	Typ.	Max.	
<b>Dynamic Characteristics<sup>b</sup></b>						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz		11		Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-15V, Frequency=1.0MHz		550		PF
C <sub>oss</sub>	Output Capacitance			120		
C <sub>rss</sub>	Reverse Transfer Capacitance			80		
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-10V, R <sub>L</sub> =10Ω, I <sub>DS</sub> =-1A, V <sub>GEN</sub> =-4.5V, R <sub>G</sub> =6Ω		13	24	Ns
T <sub>r</sub>	Turn-on Rise Time			36	66	
t <sub>d(OFF)</sub>	Turn-off Delay Time			45	82	
T <sub>f</sub>	Turn-off Fall Time			37	68	

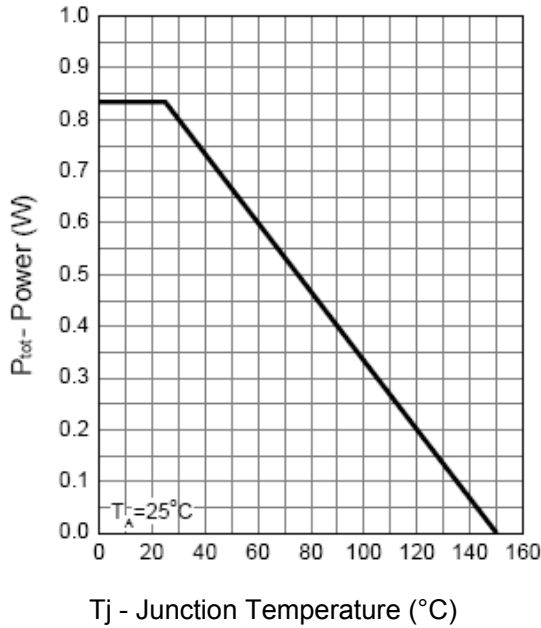
## Notes:

a : Pulse test ; pulse width ≤ 300μs, duty cycle ≤ 2%.

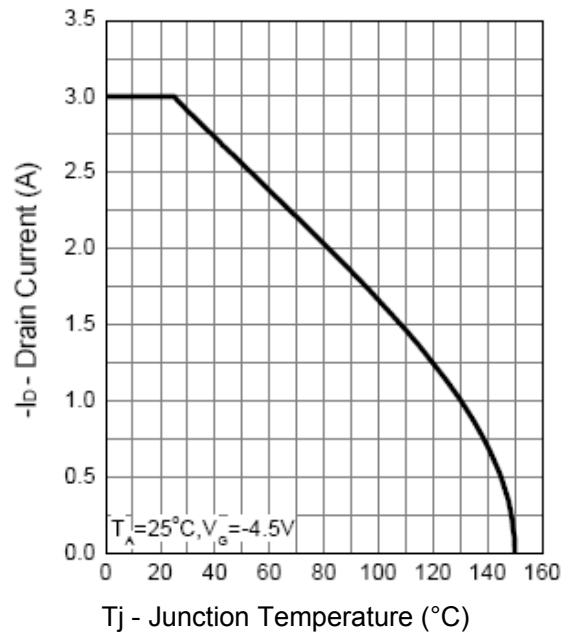
b : Guaranteed by design, not subject to production testing.

Typical Characteristics

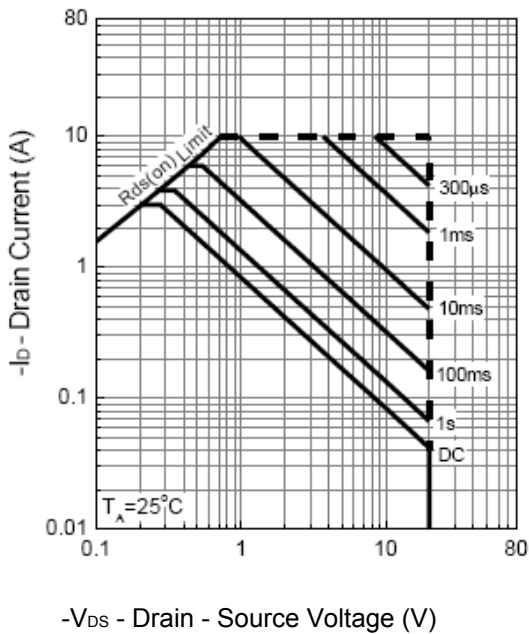
Power Dissipation



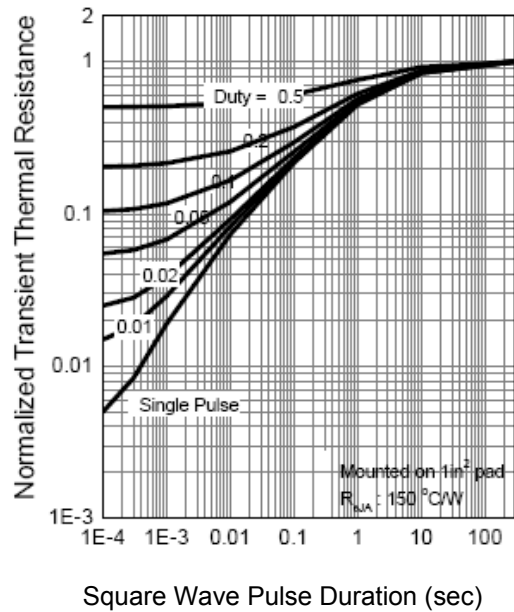
Drain Current



Safe Operation Area

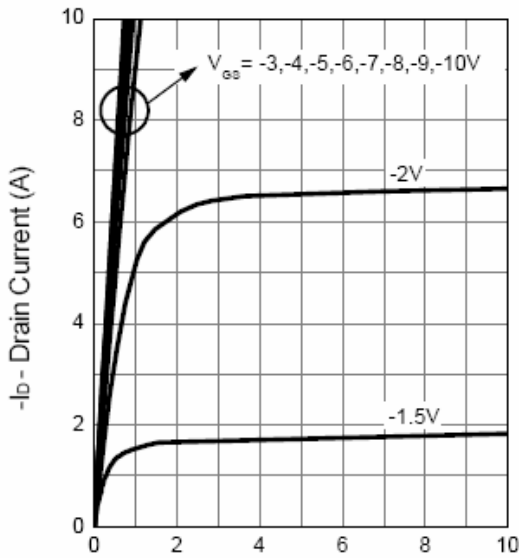


Thermal Transient Impedance



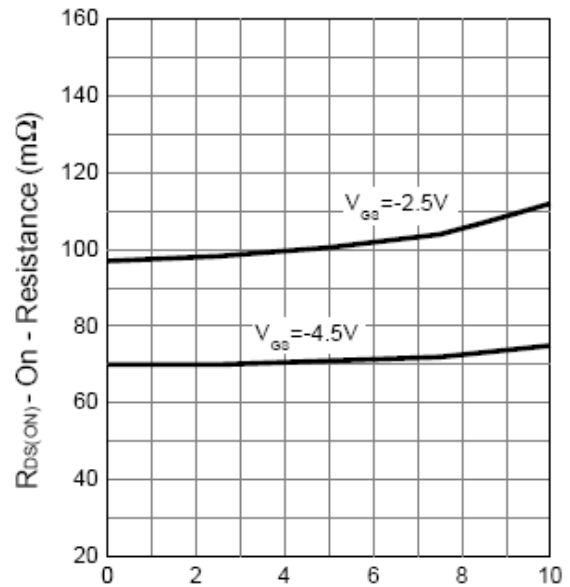
## Typical Characteristics (Cont.)

### Output Characteristics



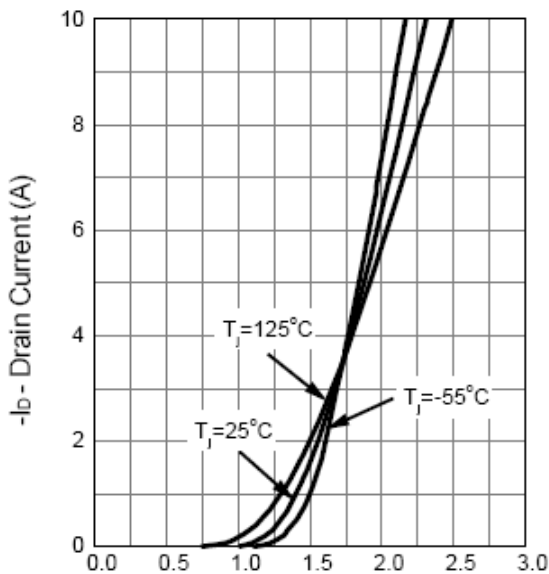
-V<sub>DS</sub> - Drain - Source Voltage (V)

### Drain-Source On Resistance



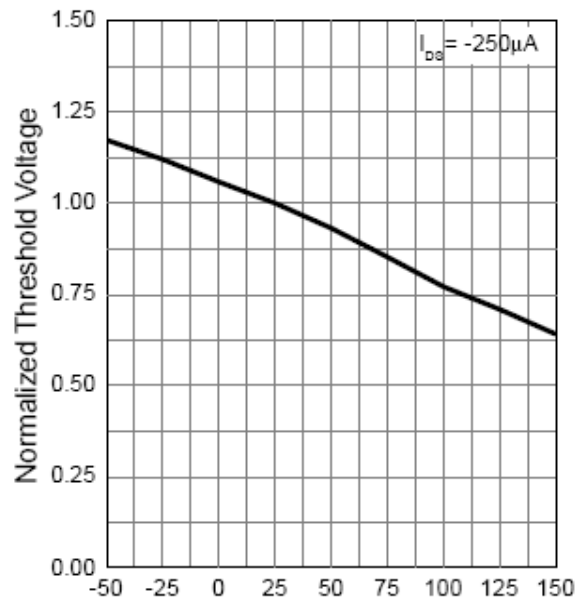
-I<sub>b</sub>- Drain Current (A)

### Transfer Characteristics



-V<sub>GS</sub> - Gate - Source Voltage (V)

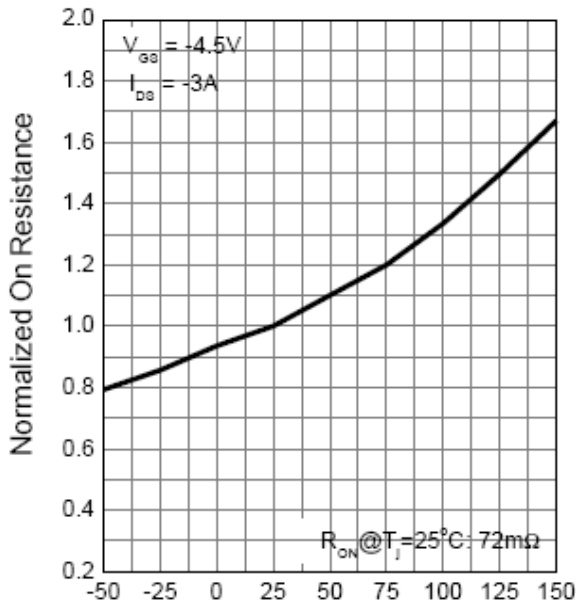
### Gate Threshold Voltage



T<sub>j</sub> - Junction Temperature (°C)

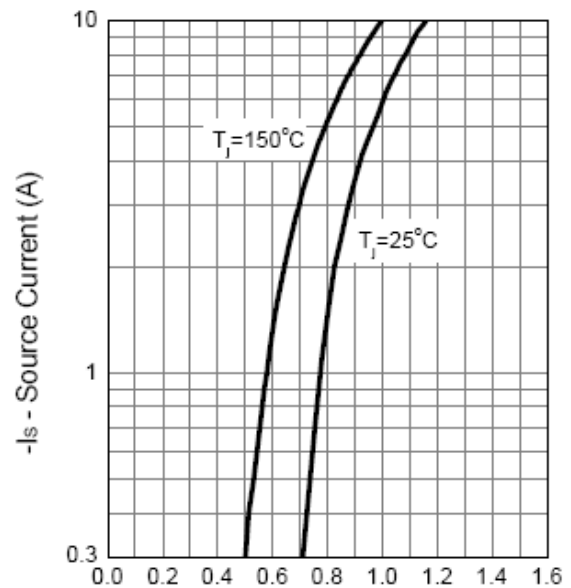
Typical Characteristics (Cont.)

Drain-Source On Resistance



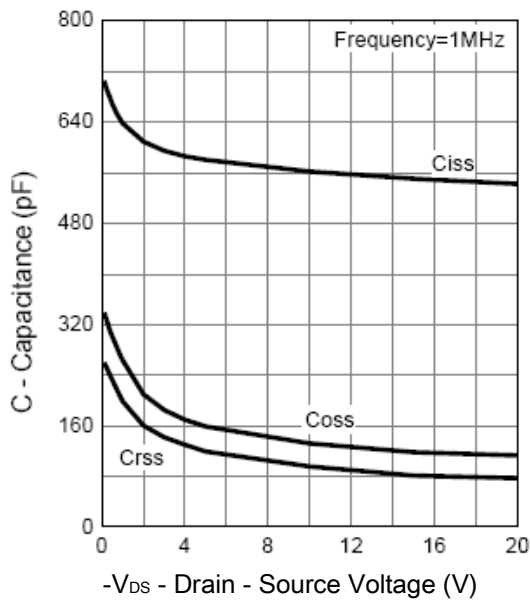
$T_j$  - Junction Temperature ( $^\circ C$ )

Source-Drain Diode Forward



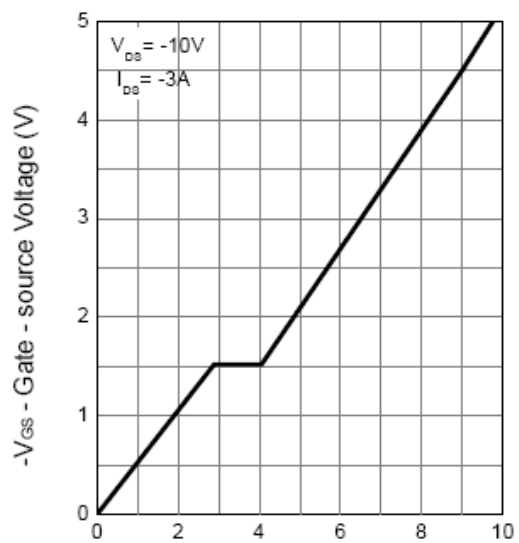
$-V_{sd}$  - Source - Drain Voltage (V)

Capacitance



$-V_{ds}$  - Drain - Source Voltage (V)

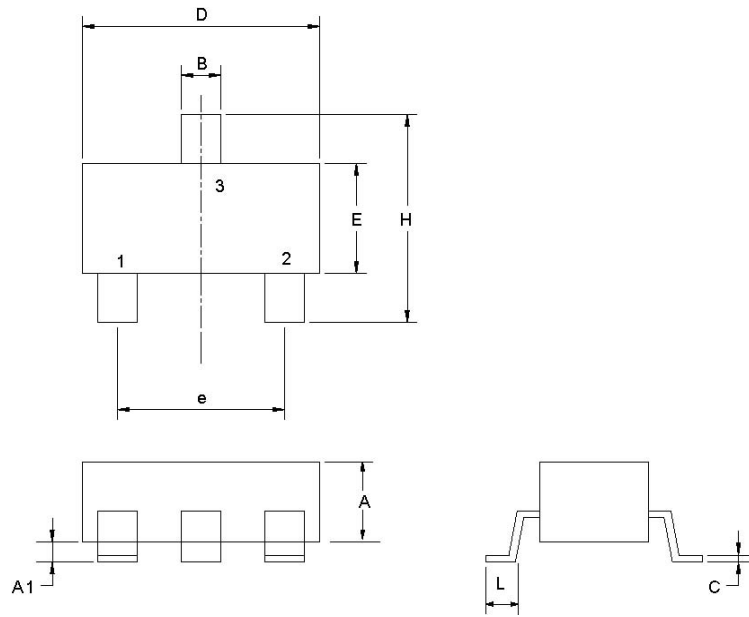
Gate Charge



$Q_g$  - Gate Charge (nC)

Packaging Information

SOT23-3L



Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
B	0.35	0.51	0.014	0.020
C	0.10	0.25	0.004	0.010
D	2.70	3.10	0.106	0.122
E	1.40	1.80	0.055	0.071
e	1.90/2.1 BSC.		0.075/0.083 BSC.	
H	2.40	3.00	0.094	0.118
L	0.37		0.015	